

SONY

CXA3219M

UHF-Band RF Modulator for VCR

Description

The CXA3219M is a UHF-band RF modulator which converts the frequency of audio and video signals. Some circuits which comprise this IC are a UHF oscillator video clamp, white clip, video modulator, audio FM modulator and an intercarrier SW.

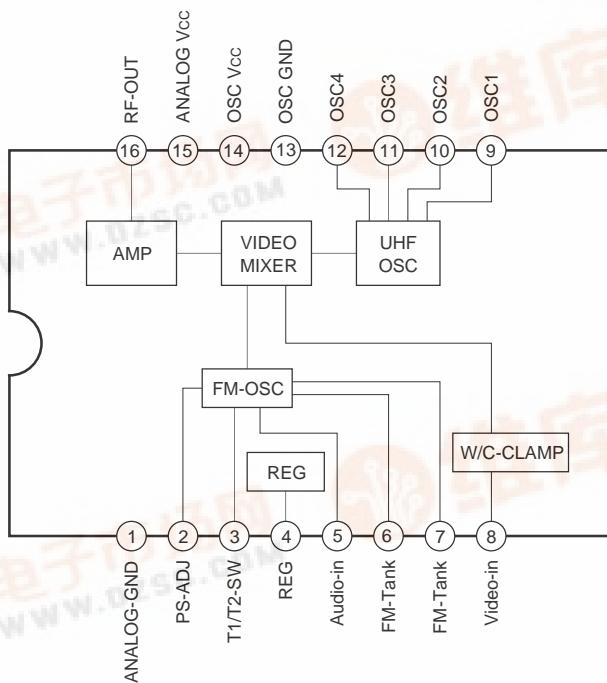
Features

- Low voltage of 5V
- Wide bandwidth 470 to 750MHz
- UHF oscillator greatly reduces external parts
- Sharp white clip circuit
- Built-in voltage regulator can accept large fluctuation of supply voltage
- Video input of 0.5Vp-p for general-purpose use
- Mixer simplifies RF unit design
- Picture/sound ratio is adjustable with external parts
- Intercarrier switch

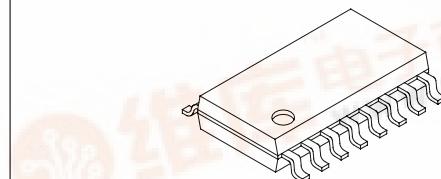
Structure

Bipolar silicon monolithic IC

Block Diagram and Pin Configuration



16 pin SOP (Plastic)



Applications

PAL system VCR

Absolute Maximum Ratings

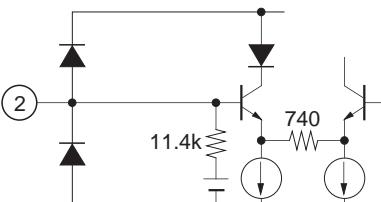
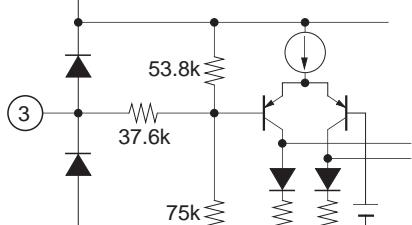
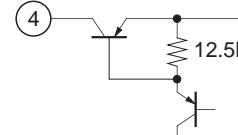
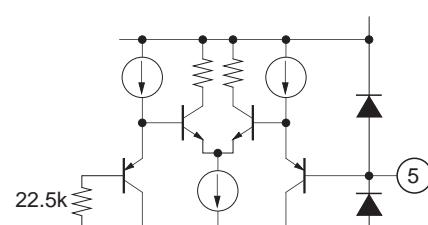
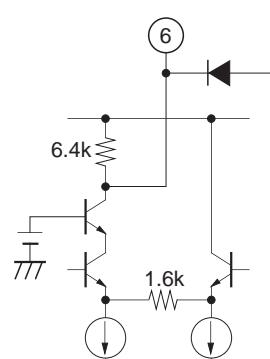
• Supply voltage	Vcc	7	V
• Operating temperature	Topr	-20 to +75	°C
• Storage temperature	Tstg	-55 to +150	°C
• Allowable power dissipation	PD	350	mW

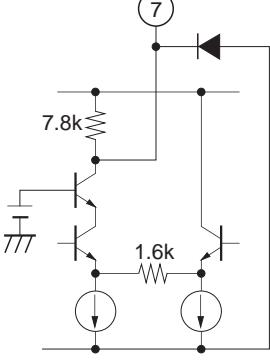
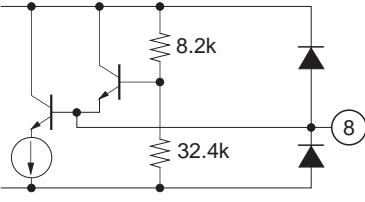
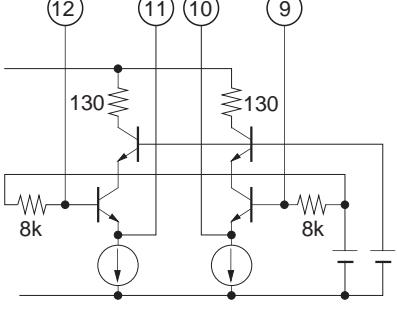
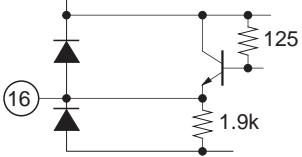
Recommended Supply Voltage Range

Supply voltage	Vcc	5.0 ± 0.5	V
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Pin Description and Equivalent Circuit

Pin No.	Symbol	Typical pin voltage [V]	Equivalent circuit	Description
1	GND1			GND for RF/audio.
2	P/S ADJ	1.8		P/S adjustment (Adding a capacitor between Pin 2 and GND increases P/S ratio.) Video modulation depth adjustment (Adding a resistor between Pin 2 and GND increases the modulation depth; adding a resistor between Pins 2 and 4 decreases the modulation depth.)
3	T1/T2 SW	2.4		T1/T2 SW. T1 for GND. T2 for OPEN.
4	REG OUT	4.1		Regulator output.
5	AUDIO IN	0		Audio input.
6	TANK1	3.1		5.5MHz audio tank coil connection.

Pin No.	Symbol	Typical pin voltage [V]	Equivalent circuit	Description
7	TANK2	2.9		6.0MHz audio tank coil connection.
8	VIDEO IN	2.6		Video input.
9 10 11 12	OSC1 OSC2 OSC3 OSC4	2.5 1.7 1.7 2.5		Oscillator pin.
13	GND2			GND for oscillator.
14	Vcc1			Power supply for oscillator.
15	Vcc2			Power supply for RF/audio.
16	RF OUT	4.1		RF output.

Electrical Characteristics 1

Refer to Electrical Characteristics Test Circuit. (Ta = 25°C, Vcc = 5V, fP = 591.25MHz)

Item	Symbol	Conditions		Min.	Typ.	Max.	Unit
Supply current	Icc	V1 (VIDEO IN) and V2 (AUDIO IN) at no signal		22	28	35	mA
Video output level	Vo	*1		78.7	81.2	83.7	dB μ V
Video modulation depth	mp	V1 = 0.5Vp-p, FLAT FIELD signal input		72	78.5	86	%
Max. video modulation depth (During limiter operation)	mp (Max.)	V1 = 1.0Vp-p, FLAT FIELD signal input		92	95.5	99	%
Chroma beat	Vcb	V1 = 4.43MHz, 0.5Vp-p sine wave input*5		68	78	—	dB
Sync crush level	Δ Sync	V1 = 0.5Vp-p, FLAT FIELD signal input Δ Sync = (1 - S/W • 10/4) × 100		—	2	5	%
Differential gain	DG	STAIR STEP signal input V1 = 0.5Vp-p*2		0	1.6	5	%
Differential phase	DP	STAIR STEP signal input V1 = 0.5Vp-p*2		-5	0	5	deg
Video 2nd-harmonic wave ratio	Vvh	V1 = 0.5Vp-p, 1MHz sine wave input*3		48	52.5	—	dB
PS ratio	Vps	V1 = no input, fs = 5.5MHz		11.5	14	16.5	dB
Audio FM modulation sensitivity	β S1 (T1) β S2 (T2)	V2 = 100mVp-p, 1kHz sine wave input fs frequency change/0.1V*6	fs = 5.5MHz fs = 6.0MHz	0.400 0.380	0.420 0.400	0.455 0.440	kHz/mV
Audio distortion	THD	V2 = 1kHz sine wave input*4		0	0.4	1	%
Audio S/N ratio	ASN	V2 = 1kHz sine wave input 0dB at fs = 5.5MHz with 60kHz deviation V1 = STAIR STEP signal input (rms measurement)		45	54	—	dB
Max. audio FM modulation depth	ms (Max.)	V2 = 1Vp-p, 1kHz sine wave input (T1) fs frequency change (kHz)/100kHz × 100		380	415	—	%
Audio 2nd-harmonic wave ratio	Vs2	Difference between video carrier (V1 = no input) and 2nd-harmonic wave, at PS ratio of 14dB conversion		52	57	—	dB

Electrical Characteristics 2

1. Video S/N	50dB (min.), 58dB (typ.)
2. Video amplitude frequency characteristics (at 1MHz reference)	Within ± 1 dB at 0.5 to 5MHz
3. APL variation (Normalized to APL 50%)	Within $\pm 2\%$ at 10 to 90%
4. Pin 5 input impedance	1M Ω and above
5. Pin 8 input impedance	1M Ω and above

*¹ Spectrum analyzer with 50 Ω input impedance should be used to test video output level. Measured value V_o (dBm) is used to calculate output according to the following relationship:

$$\text{Output (dB μ)} = V_o \text{ (dBm)} + 107 \quad 50\Omega \text{ terminal direct reading value}$$

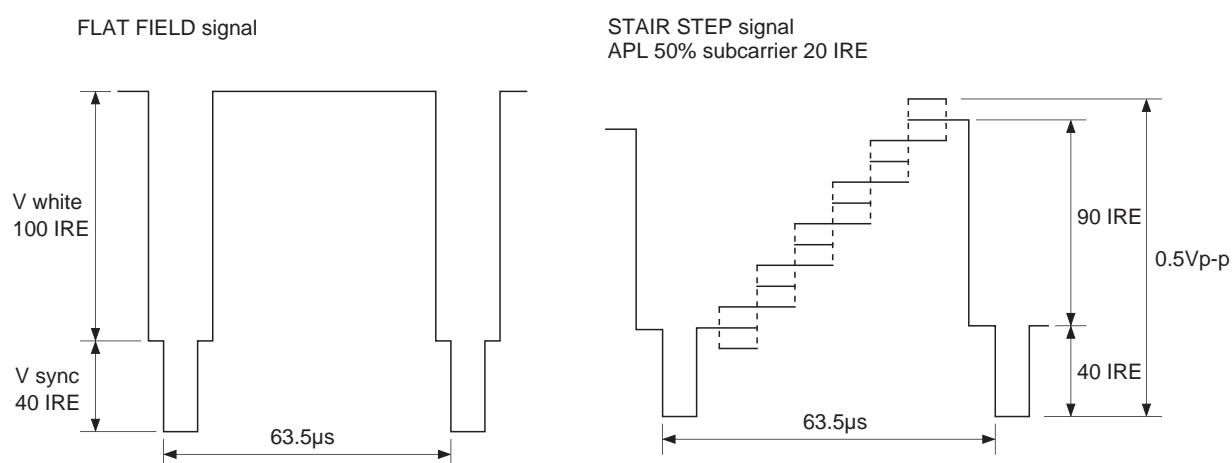
*² Measured after demodulating by standard demodulator.

*³ fc + 2MHz component of V₁ carrier (fc) level.

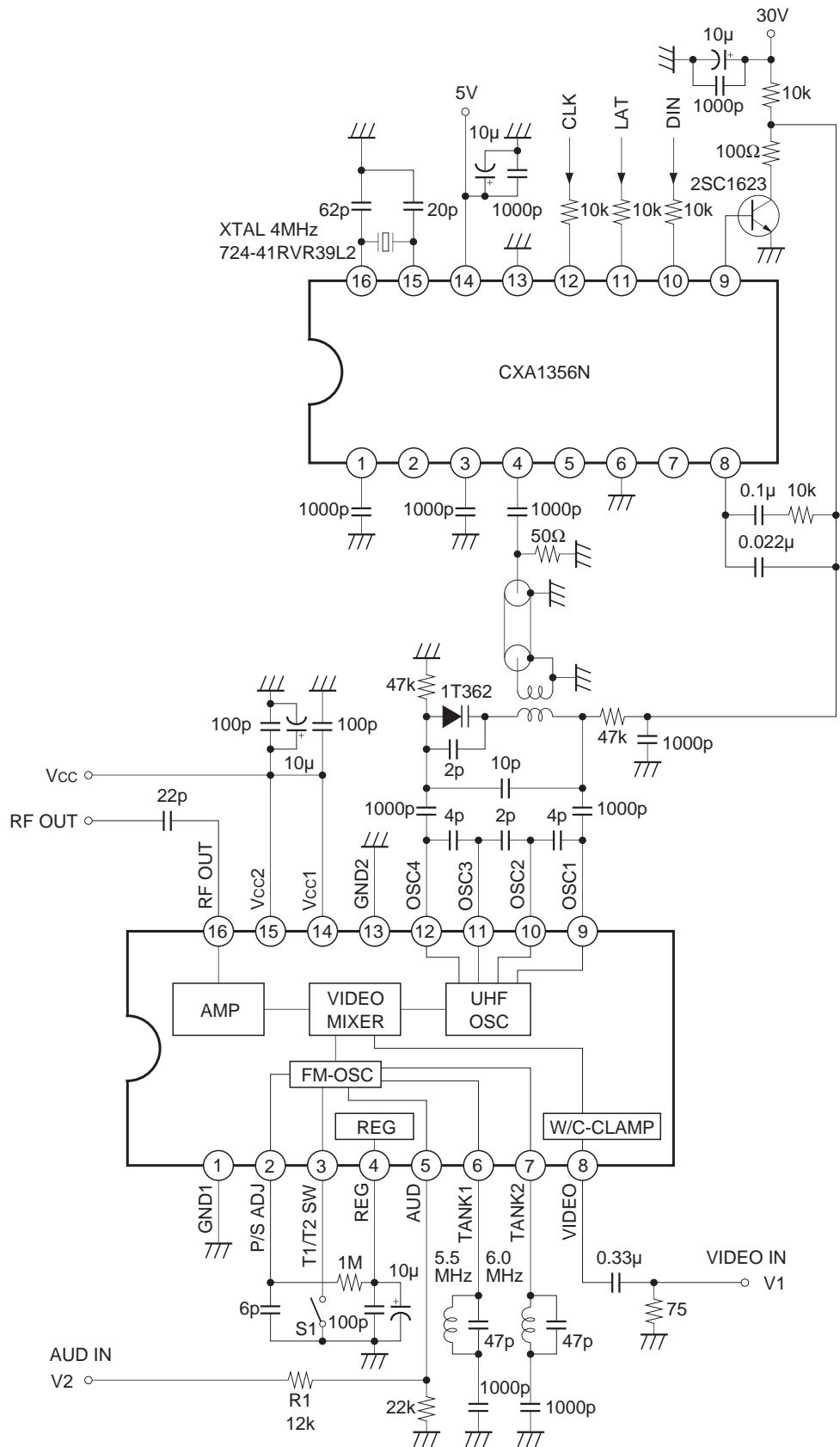
*⁴ Adjust the V₂ level to obtain an FM deviation of ± 30 kHz and measure the harmonic distortion after demodulating V_o with a standard demodulator.

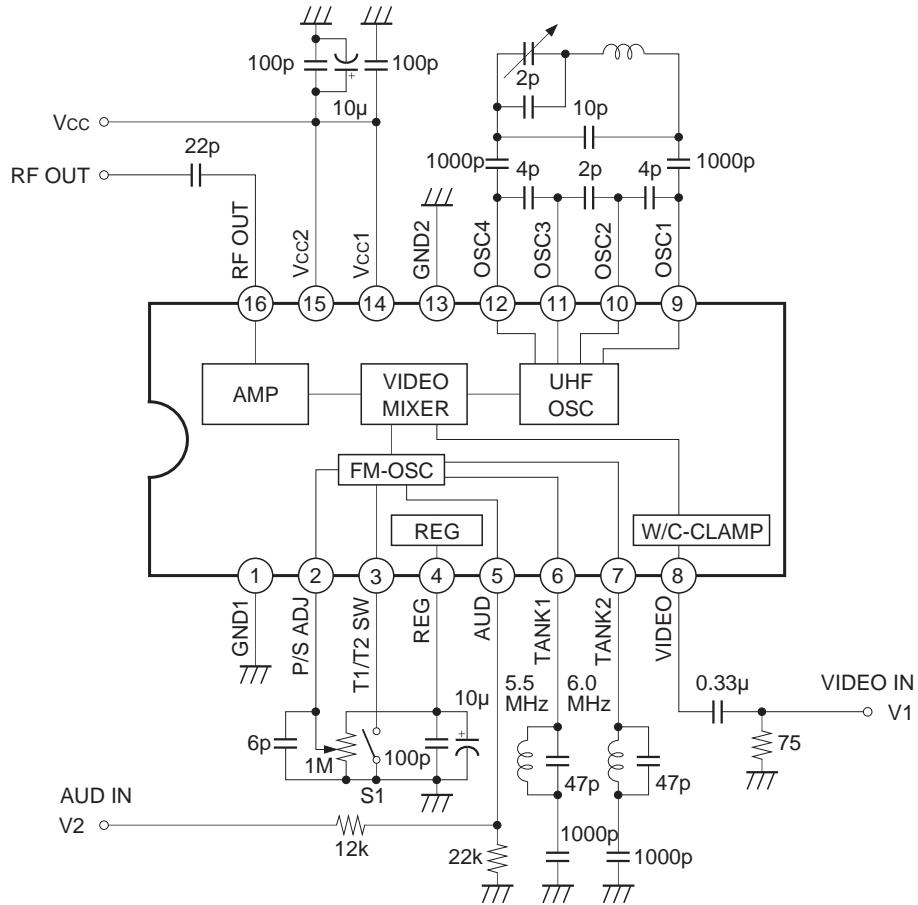
*⁵ Video determined by measuring ratio (dB) of chroma beat to video carrier level when V₁ = no signal by spectrum analyzer.

*⁶ R1 (12k Ω) of the Electrical Characteristics Test Circuit is added for obtaining a better match between the audio modulation sensitivity classifications and the actual pre-emphasis.

Input Waveform

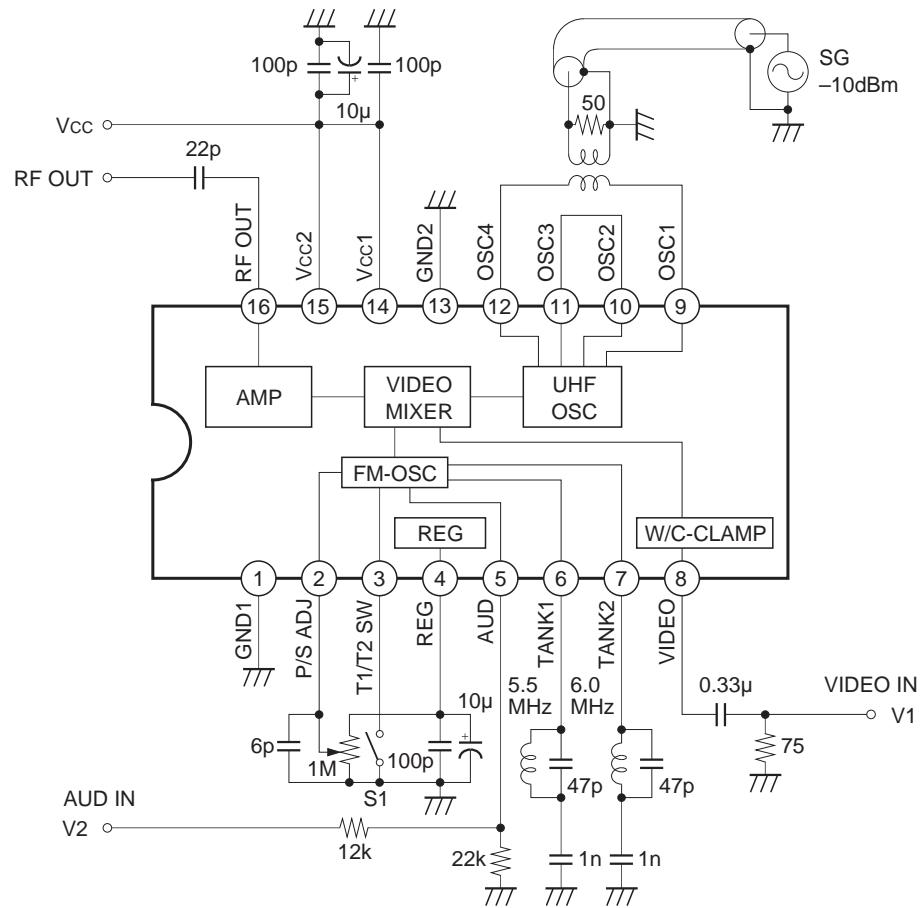
Electrical Characteristics Test Circuit



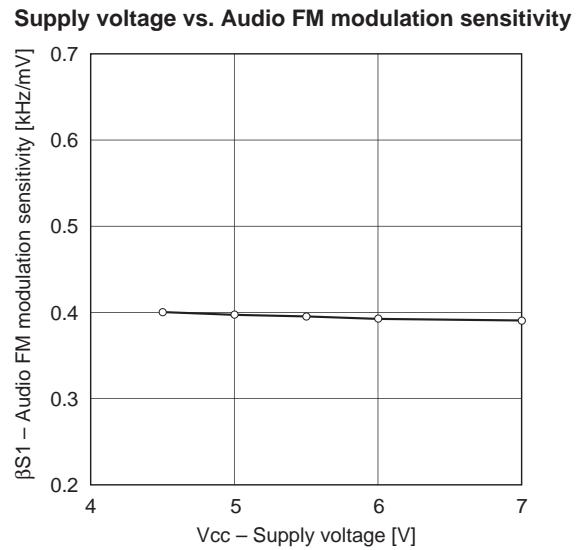
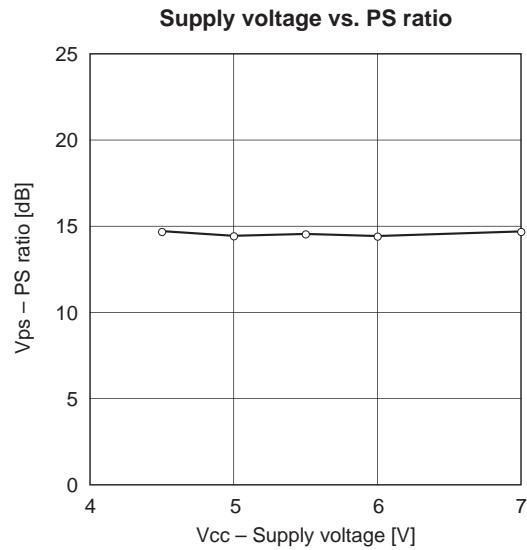
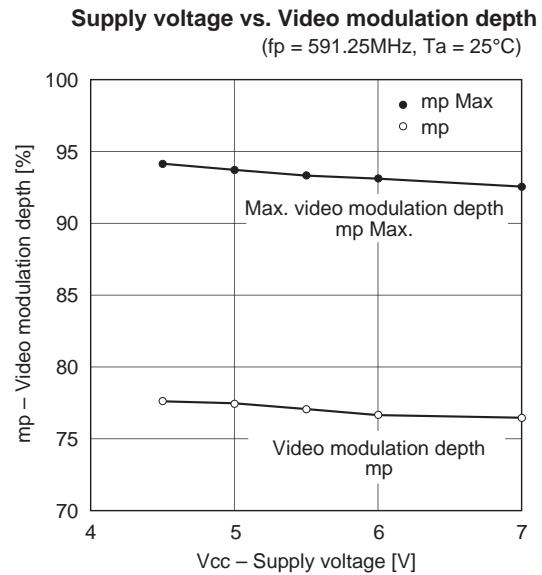
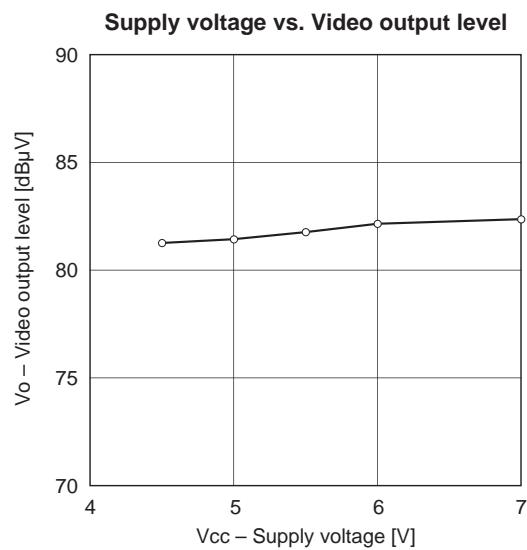
Application Circuit 1

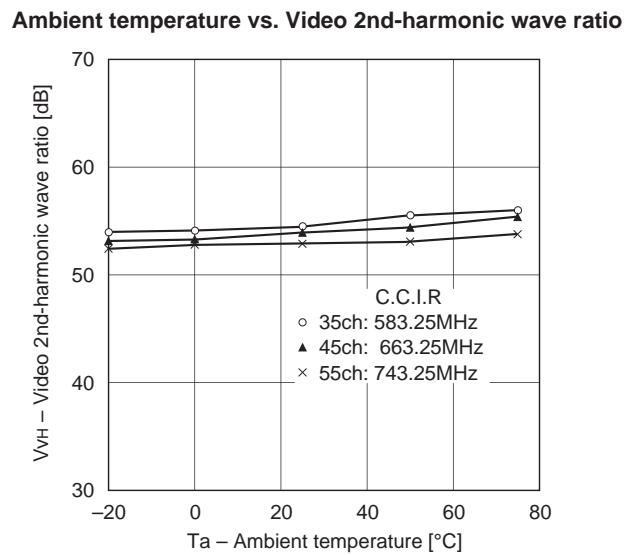
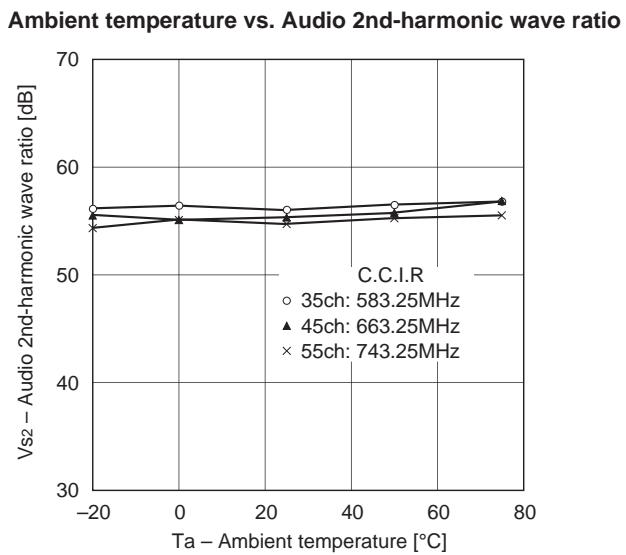
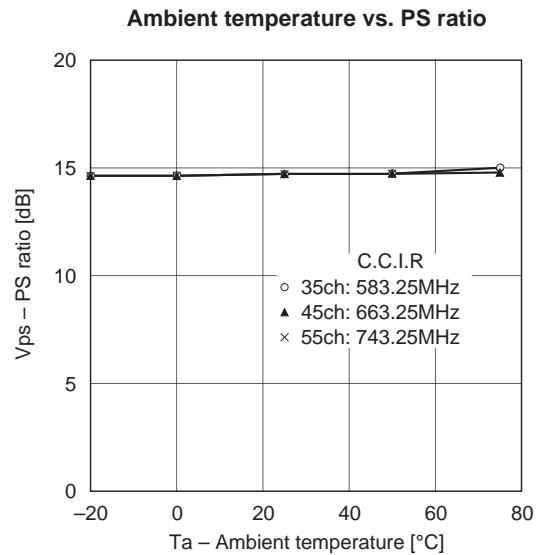
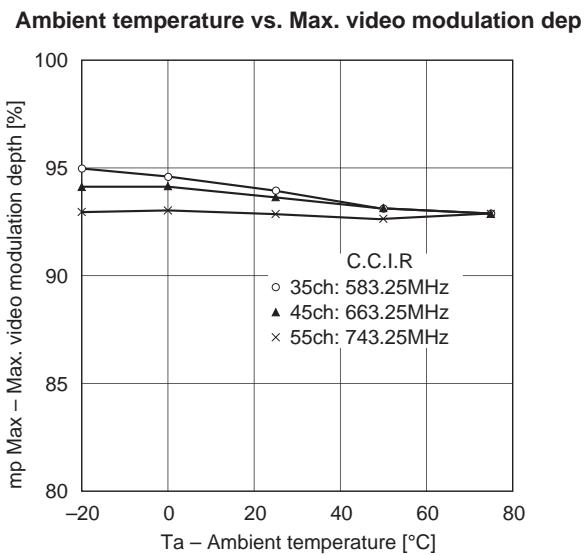
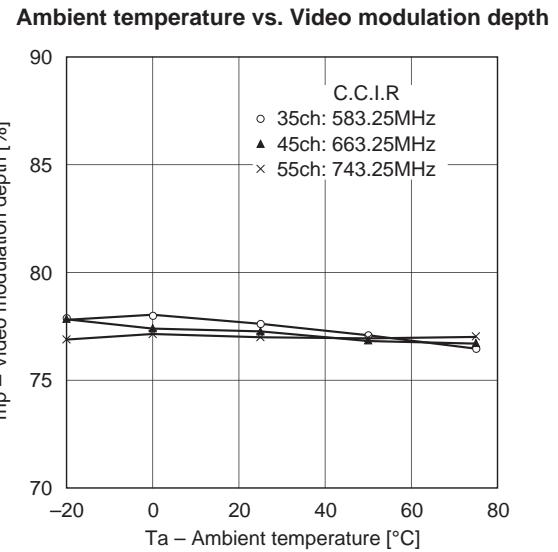
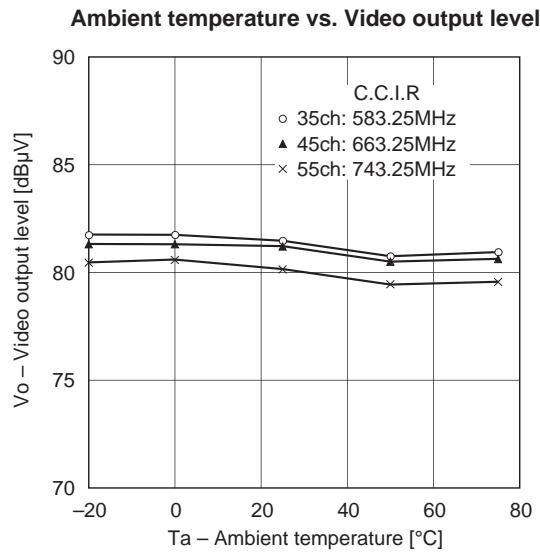
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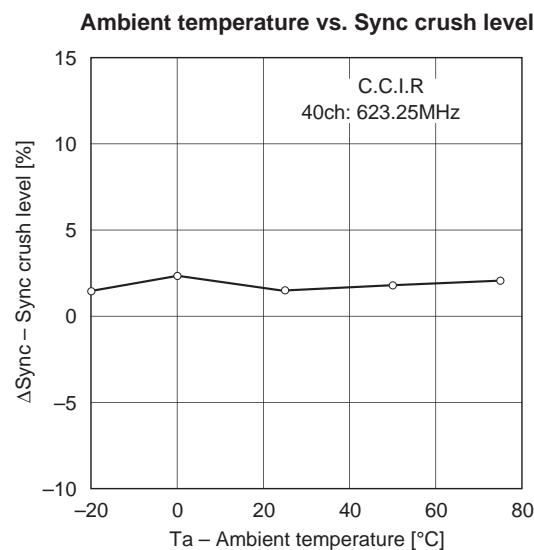
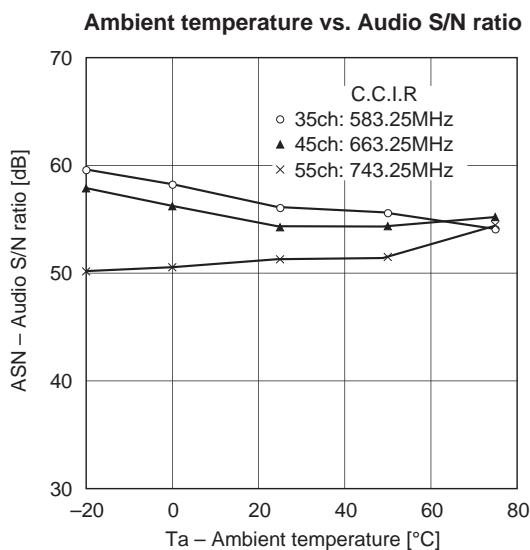
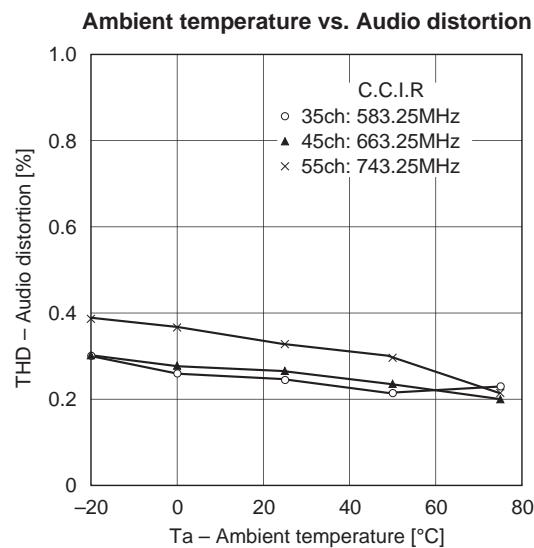
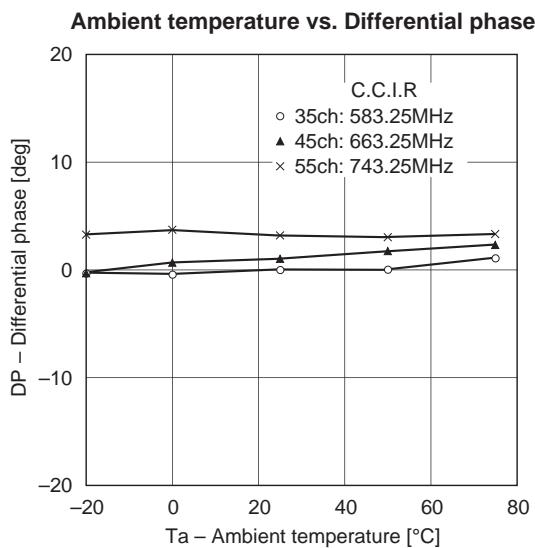
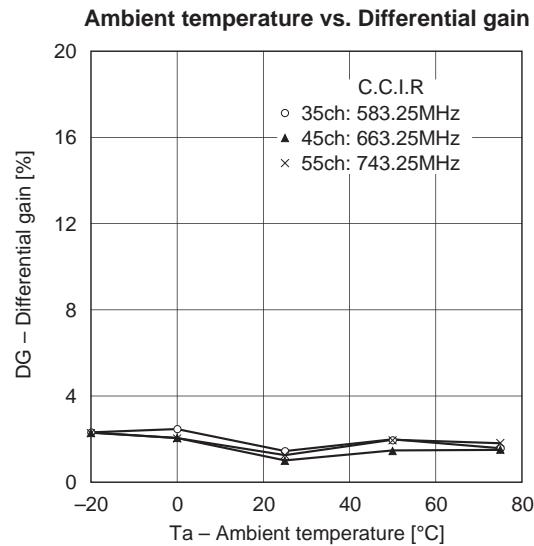
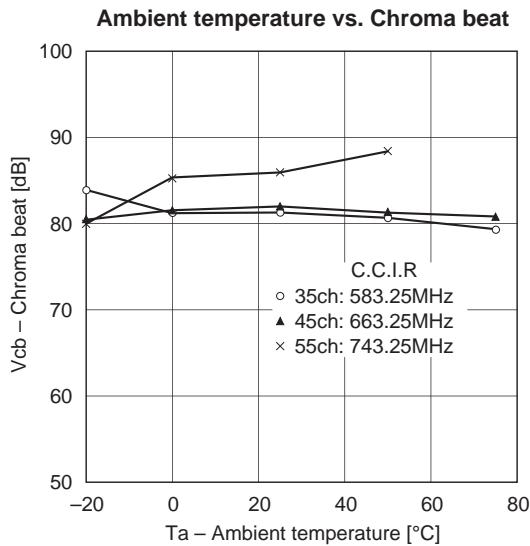
Application Circuit 2

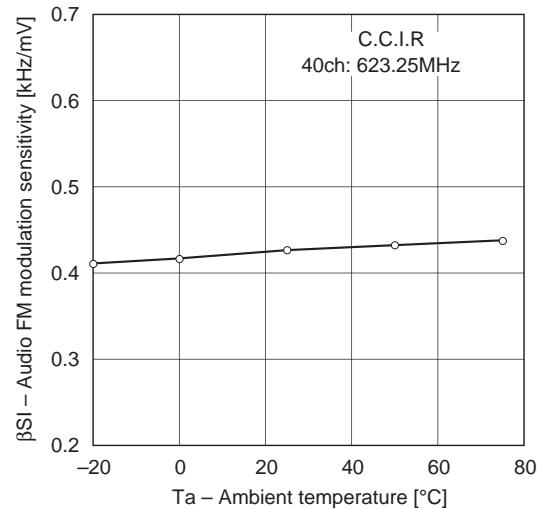
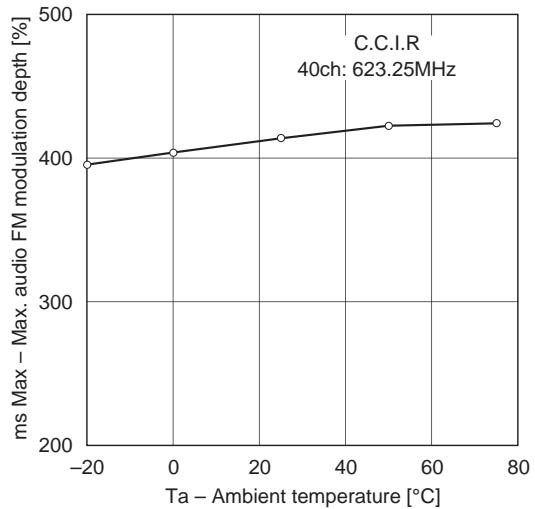


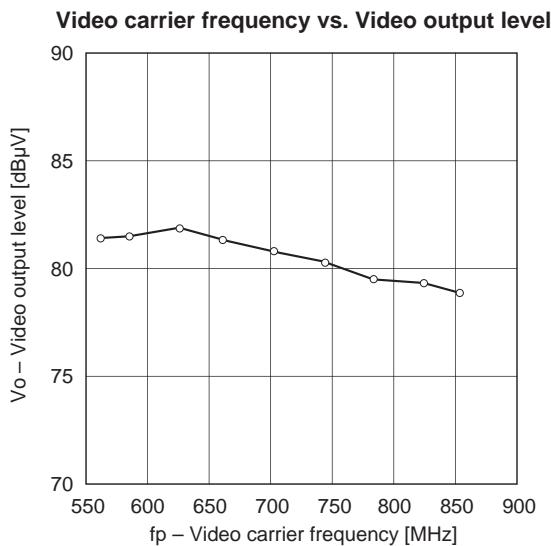
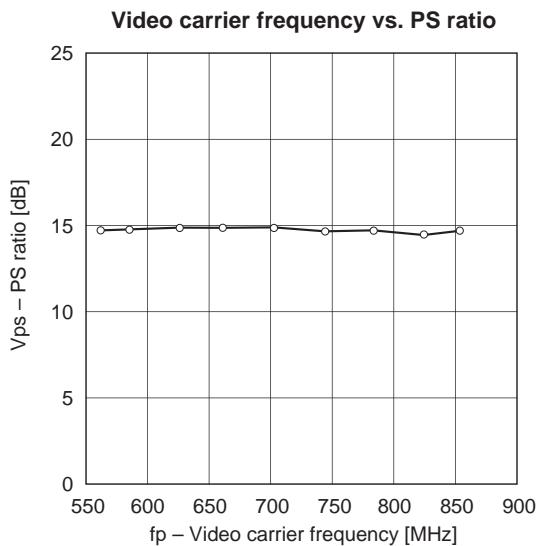
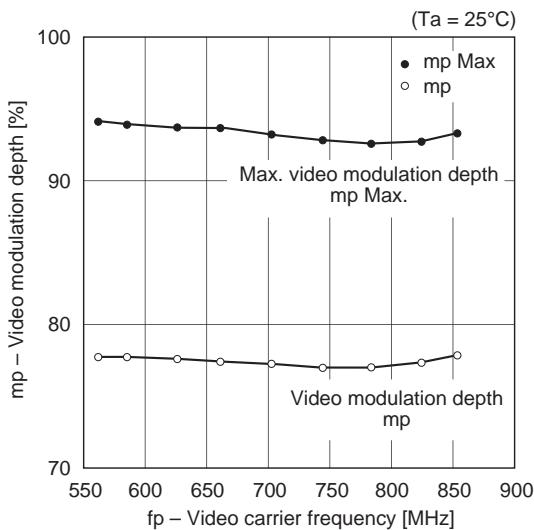
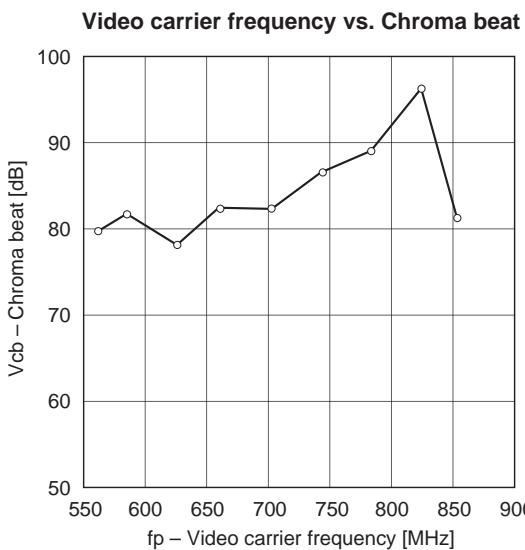
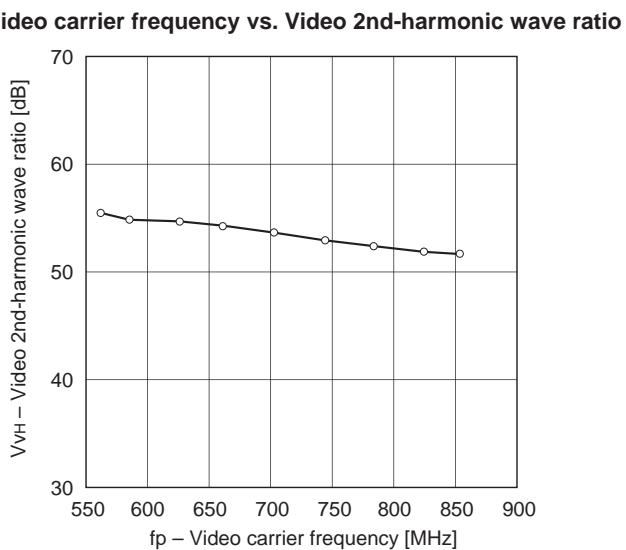
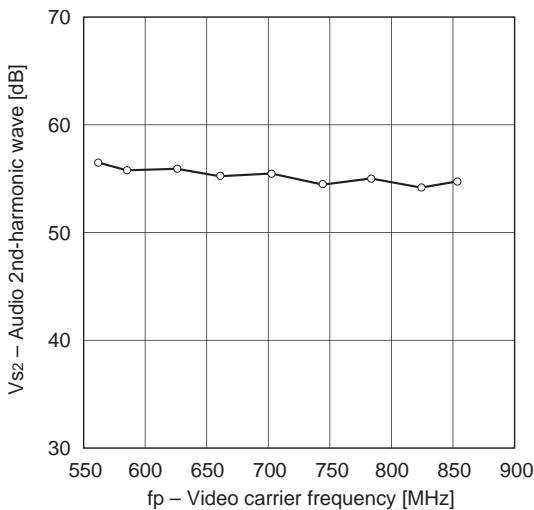
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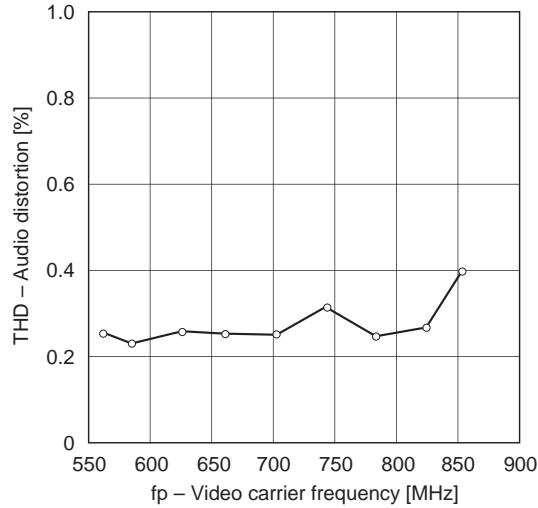
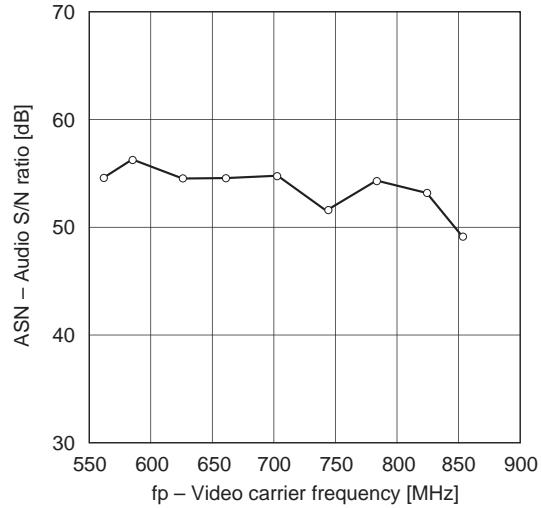
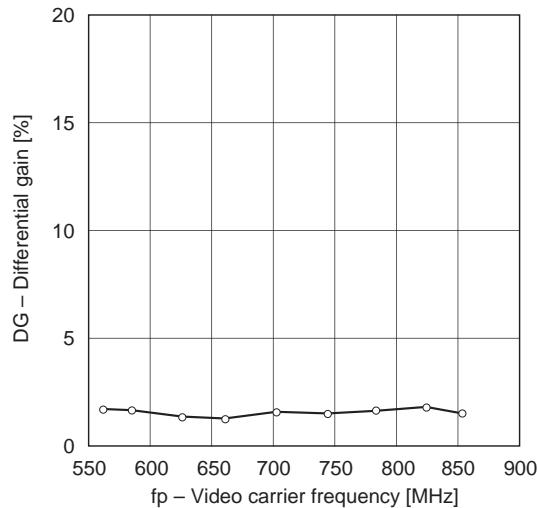
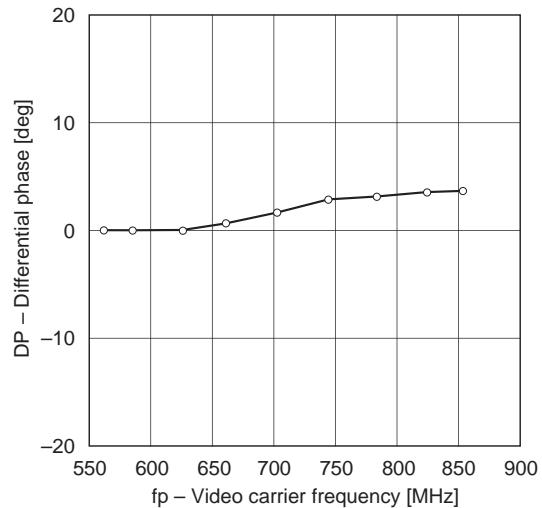
Example of Representative Characteristics





Ambient temperature vs. Audio FM modulation sensitivity**Ambient temperature vs. Max. audio FM modulation depth**

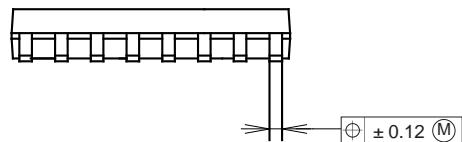
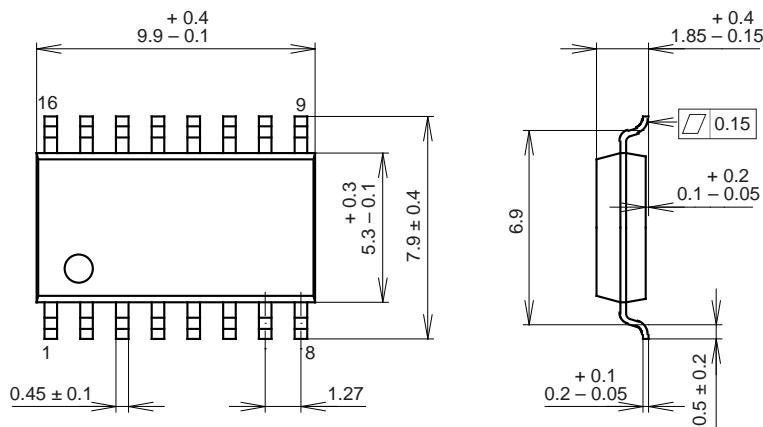
**Video carrier frequency vs. Video modulation depth****Video carrier frequency vs. Audio 2nd-harmonic wave ratio**

Video carrier frequency vs. Audio distortion**Video carrier frequency vs. Audio S/N ratio****Video carrier frequency vs. Differential gain****Video carrier frequency vs. Differential phase**

Package Outline

Unit: mm

16PIN SOP (PLASTIC) 300mil

**PACKAGE STRUCTURE**

SONY CODE	SOP-16P-L01
EIAJ CODE	*SOP016-P-0300-A
JEDEC CODE	-----

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE WEIGHT	0.2g